

Front and Back Side Non-Destructive Laser Debugging System for Failure Analysis Industry

SAN JOSE, Calif. – (BUSINESS WIRE) -- Checkpoint Technologies, LLC, noted supplier of laser scanning and photon emission microscopy systems for the failure analysis industry, announces the release of InfraScan(tm) TDM. This unique wafer probing system is capable of imaging the front-side and backside of the die. The InfraScan TDM can be configured along with the InfraScan™ LTM providing the user with superior non-destructive optical probing of the smallest transistors available at 22nm.

"Checkpoint Technologies has designed the InfraScan(tm) TDM so that customer's are capable of getting the best SIL images from a top-down system, explained, Michael Jupina, Checkpoint Technologies Director of Sales and Marketing. "It allows customer to electrically probe their part while getting state-of-the-art high-resolution imaging."

The InfraScan TDM offers world-class photon emission and is compatible with any SIL that is designed by Checkpoint Technologies up to 3.0 NA. In addition the tool is capable of running both TIVA and LIVA. Checkpoint Technologies InfraScan product line offers state-of-the-art design and exceptional reliability with near zero downtime for laser timing measurement, photon emission microscopy and laser debugging.

About Checkpoint Technologies

Founded in 1995, Checkpoint Technologies develops and manufactures optical failure analysis tools used by semiconductor manufacturers to improve the speed and reliability of integrated circuits for the failure analysis industry. Checkpoint Technologies is headquartered in San Jose, California USA with worldwide sales and service. www.checkpointtechnologies.com

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